

STACKED SEMICONDUCTOR DEVICE

ABSTRACT OF THE DISCLOSURE

A stacked semiconductor device has a substrate having a conductor pattern
5 and a cavity. A first die is received in the cavity of the cavity of the substrate and is
electrically connected to the conductor pattern via wires. An adhesive layer is printed
on a top of the first die. A second die is stacked on the first die via the adhesive layer
and is electrically connected to the conductor pattern via wires, and An insulating layer
provided on the substrate, wherein the insulating layer cover the first die and the
10 second die and has a portion thereof received in the cavity to bond the first die.